

**Abstract of the Disclosure**

A printed circuit board including electrical circuitry formed on an outer surface of the printed circuit board, the circuitry comprising copper or a copper alloy; a final finish on the circuitry, the final finish including a coating of tin on the copper or copper alloy circuitry; and an alloy cap layer on the tin coating, the alloy cap layer comprising at least two immersion-platable metals. The immersion platable metals in the alloy cap layer may be at least two metals selected from tin, silver, bismuth, copper, nickel, lead, zinc, indium, palladium, platinum, gold, cadmium, ruthenium and cobalt. The circuitry remains whisker free and solderable.

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